



Description

JMT N-channel Enhancement Mode Power MOSFET

Features

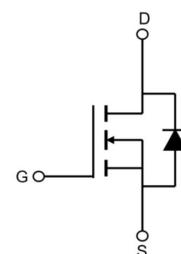
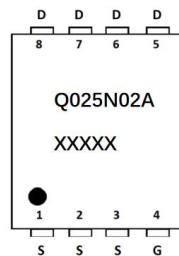
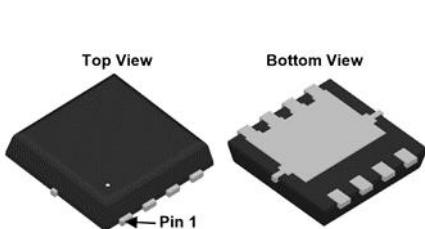
- 20V,80 A
- $R_{DS(ON)} < 2.9m\Omega$ @ $V_{GS} = 10V$
- $R_{DS(ON)} < 3.5m\Omega$ @ $V_{GS} = 4.5V$
- $R_{DS(ON)} < 5.6m\Omega$ @ $V_{GS} = 2.5V$
- Lead free and Green Device Available
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

- Load Switch
- PWM Application
- Power management



100% UIS TESTED!
100% ΔV_{ds} TESTED!



PDFN3.3X3.3-8L

Marking and pin Assignment

Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
Q025N02A	JMTQ025N02A	TAPING	PDFN3.3X3.3-8L	13inch	5000	50000

Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		20	V
V_{GSS}	Gate-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$	80	A
		$T_c = 100^\circ C$	53	A
I_{DM}	Pulsed Drain Current ^{note1}		320	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		150	mJ
P_D	Power Dissipation	$T_c = 25^\circ C$	30	W
R_{eJC}	Thermal Resistance, Junction to Case		4.2	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$



JMTQ025N02A

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{GS}=\pm 12\text{V}$, $V_{DS}=0\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	0.5	0.7	1.1	V
$R_{DS(\text{on})}$	Static Drain-Source On-Resistance note3	$V_{GS}=10\text{V}$, $I_D=30\text{A}$	-	2.2	2.9	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=20\text{A}$	-	2.5	3.5	
		$V_{GS}=2.5\text{V}$, $I_D=10\text{A}$	-	3.7	5.6	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=10\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	-	5392	-	pF
C_{oss}	Output Capacitance		-	902	-	pF
C_{rss}	Reverse Transfer Capacitance		-	866	-	pF
Q_g	Total Gate Charge	$V_{DS}=10\text{V}$, $I_D=40\text{A}$, $V_{GS}=4.5\text{V}$	-	52	-	nC
Q_{gs}	Gate-Source Charge		-	6.3	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	25	-	nC
Switching Characteristics						
$t_{d(\text{on})}$	Turn-On Delay Time	$V_{DS}=10\text{V}$, $I_D=40\text{A}$, $R_G=1\Omega$, $V_{GS}=4.5\text{V}$	-	7.5	-	ns
t_r	Turn-On Rise Time		-	25	-	ns
$t_{d(\text{off})}$	Turn-Off Delay Time		-	57	-	ns
t_f	Turn-Off Fall Time		-	37	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current		-	-	80	A
I_{sM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	320	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_{SD}=30\text{A}$, $T_J=25^\circ\text{C}$	-	-	1.2	V
t_{rr}	Reverse Recovery Time	$T_J=25^\circ\text{C}$, $I_F=40\text{A}$, $dI/dt = 220\text{A}/\mu\text{s}$	-	41	-	ns
Q_{rr}	Reverse Recovery Charge		-	68	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^\circ\text{C}$, $V_{DD}=10\text{V}$, $V_G=10\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=24.5\text{A}$

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

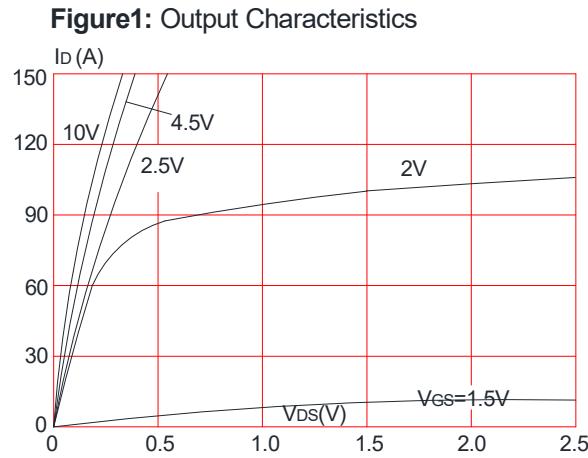


Figure 2: Typical Transfer Characteristics

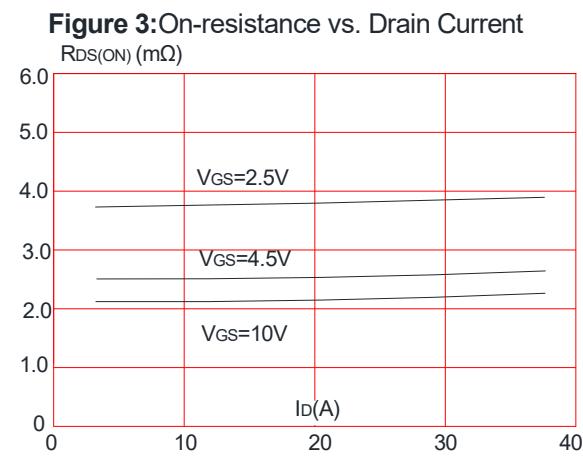
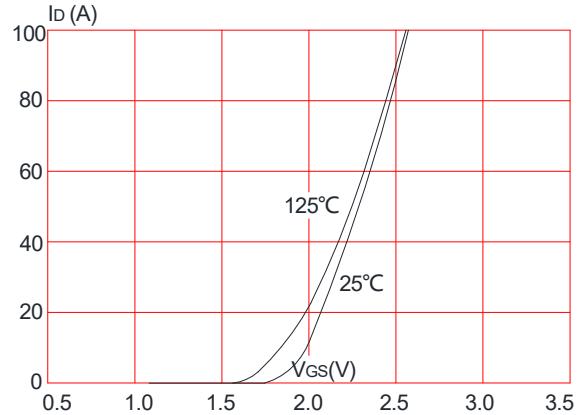


Figure 4: Body Diode Characteristics

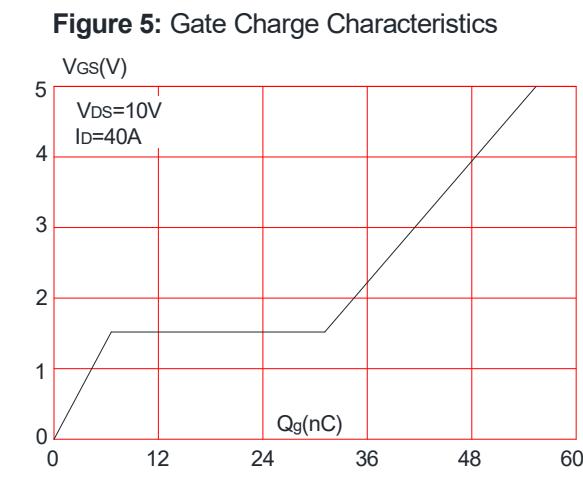
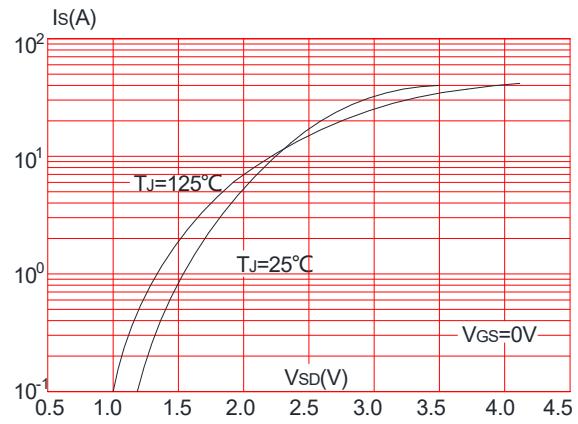


Figure 6: Capacitance Characteristics

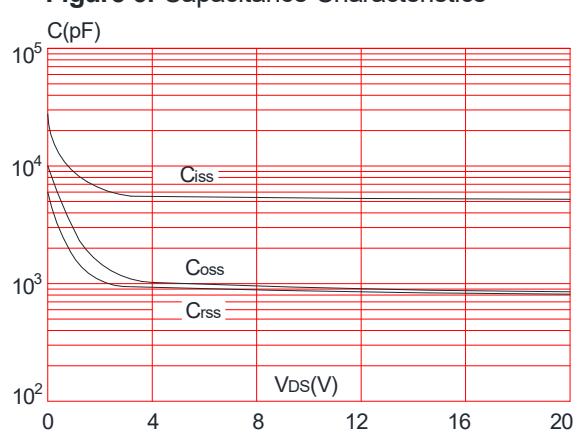


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

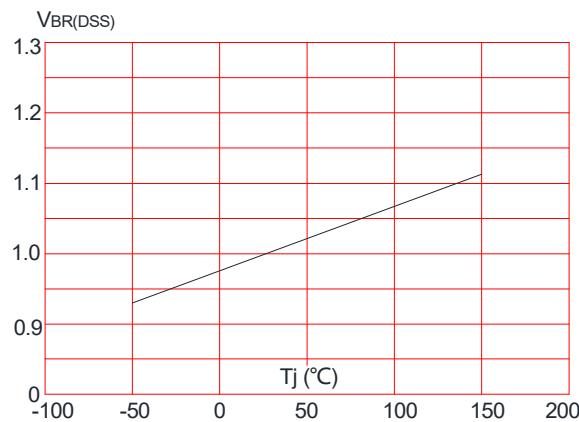


Figure 8: Normalized on Resistance vs. Junction Temperature

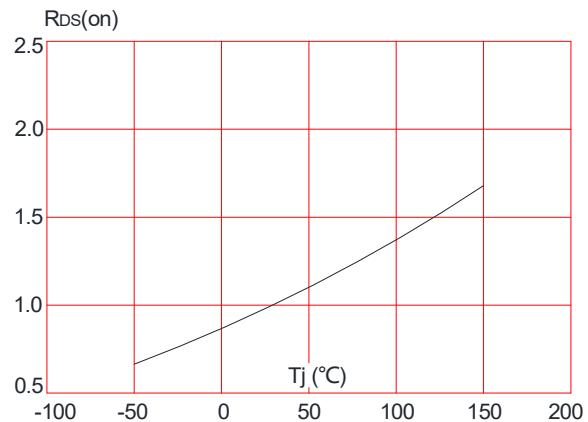


Figure 9: Maximum Safe Operating Area

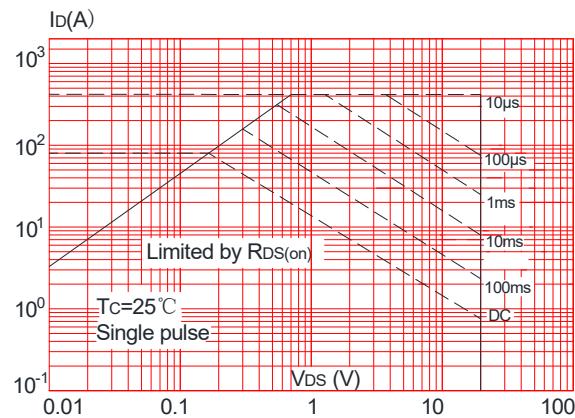


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

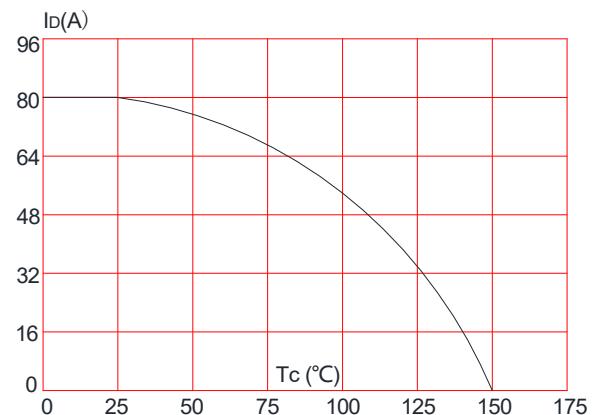
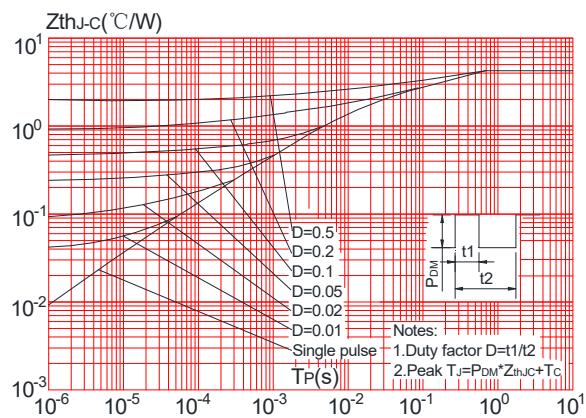


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



Test Circuit

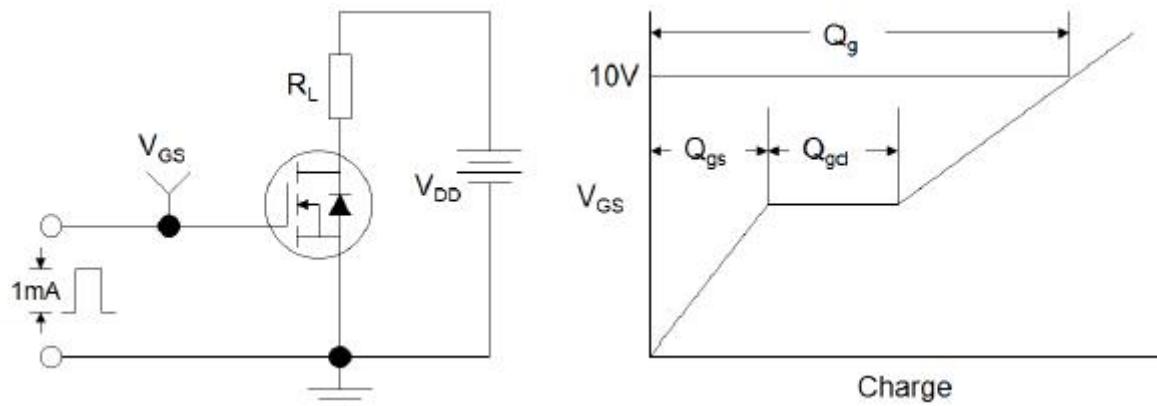


Figure1:Gate Charge Test Circuit & Waveform

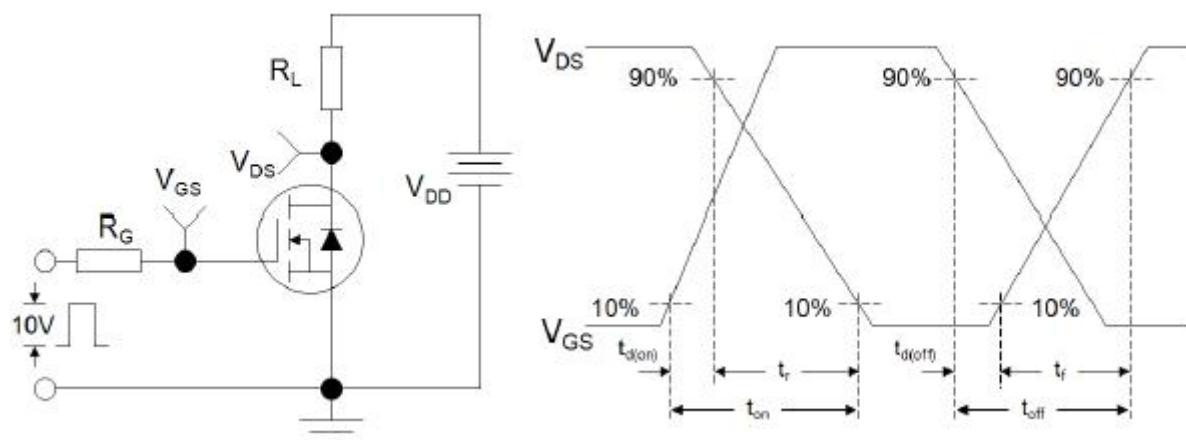


Figure 2: Resistive Switching Test Circuit & Waveforms

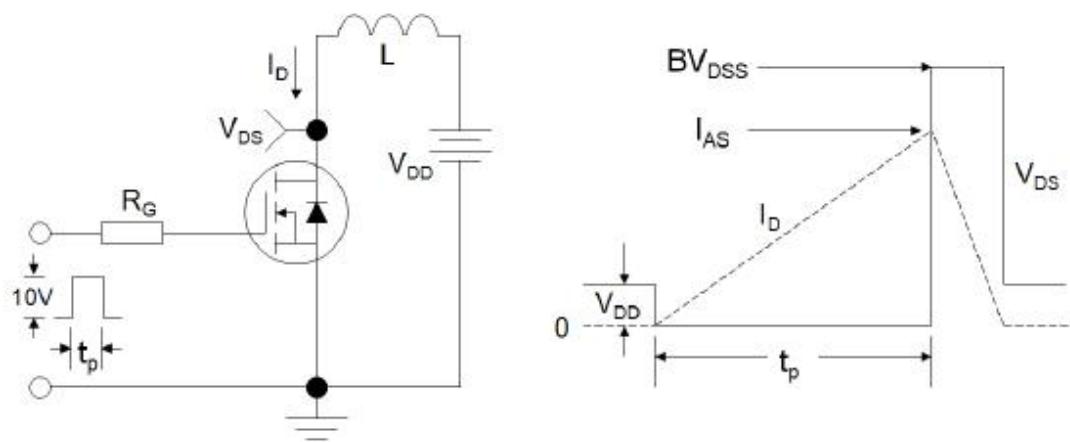
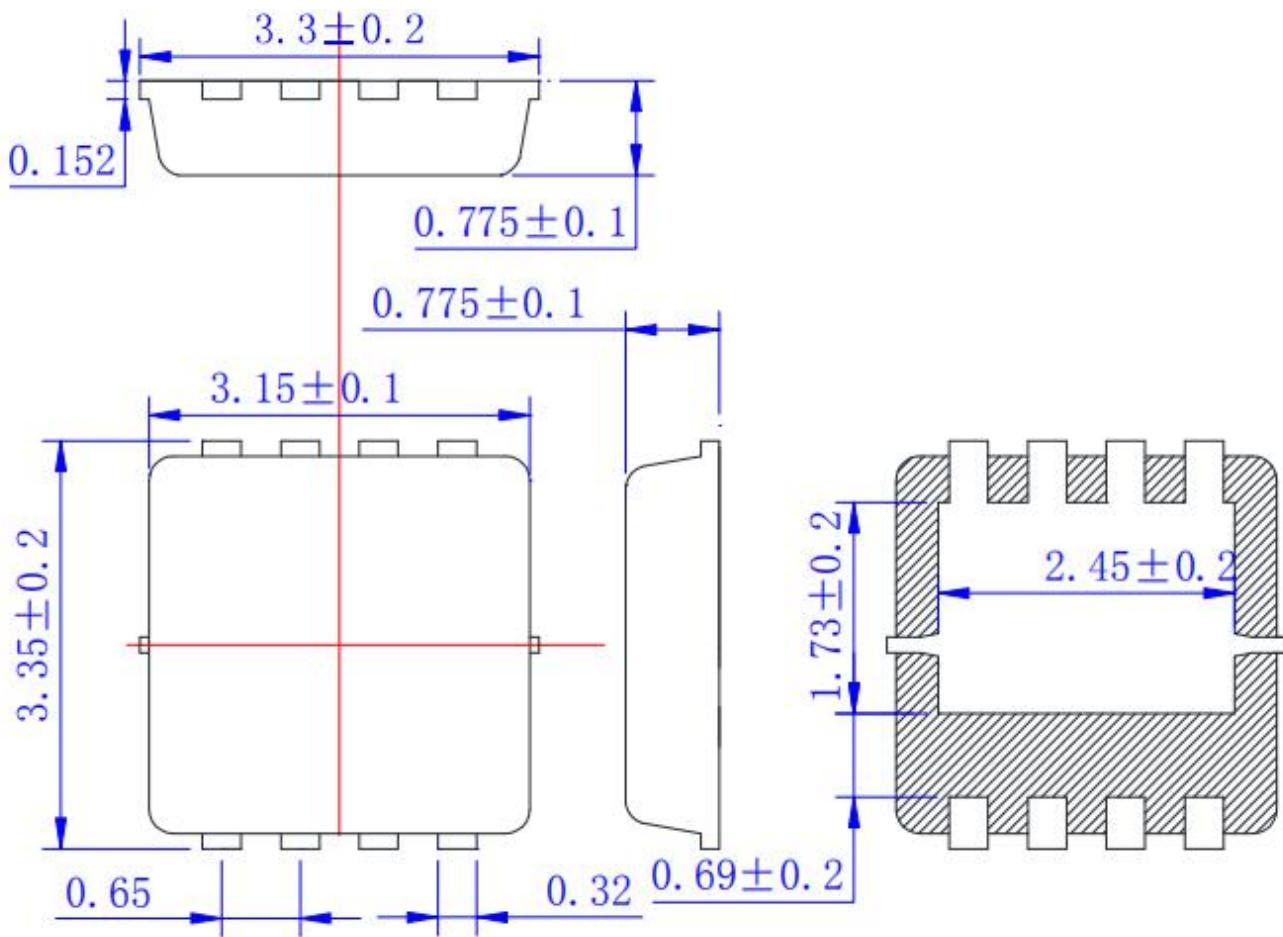


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data- PDFN3.3X3.3-8L



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